

# BT145-800R Thyristors

## ●DESCRIPTION:

Planar passivated Silicon Controlled Rectifier (SCR) in a TO220 plastic package intended for use in applications requiring high bidirectional blocking voltage capability, high current inrush capability and high thermal cycling performance.

## ●Features and benefits

- AC power control
- High bidirectional blocking voltage capability
- High thermal cycling performance
- Planar passivated for voltage ruggedness and reliability
- High junction operating temperature capability ( $T_{j(max)} = 150\text{ }^{\circ}\text{C}$ )
- Package meets UL94V0 flammability requirement
- Package is RoHS compliant
- IEC 61000-4-4 fast transient

## ●Applications

- Capacitive Discharge Ignition (CDI)
- Crowbar protection
- Inrush protection
- Motor control
- Voltage regulation
- High junction operating temperature capability ( $T_{j(max)} = 150\text{ }^{\circ}\text{C}$ )

## ●Quick reference data

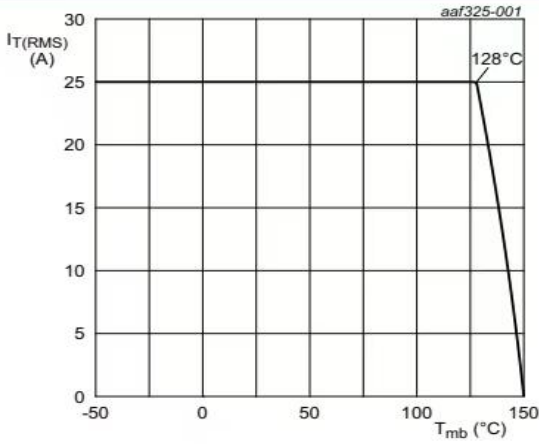
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Absolute maximum rating</b>						
$V_{RRM}$	repetitive peak reverse voltage		-	-	800	V
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_{mb} \leq 128\text{ }^{\circ}\text{C}$ ; Fig. 1; Fig. 2; Fig. 3	-	-	25	A
$I_{TSM}$	non-repetitive peak on-state current	half sine wave; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$ ; $t_p = 10\text{ ms}$ ; Fig. 4; Fig. 5	-	-	300	A
		half sine wave; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$ ; $t_p = 8.3\text{ ms}$	-	-	330	A
$T_j$	junction temperature		-	-	150	$^{\circ}\text{C}$
<b>Static characteristics</b>						
$I_{GT}$	gate trigger current	$V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; $T_j = 25\text{ }^{\circ}\text{C}$ ; Fig. 7	1.5	-	15	mA
$I_H$	holding current	$V_D = 12\text{ V}$ ; $T_j = 25\text{ }^{\circ}\text{C}$ ; Fig. 9	-	-	60	mA
$V_T$	on-state voltage	$I_T = 30\text{ A}$ ; $T_j = 25\text{ }^{\circ}\text{C}$ ; Fig. 10	-	1.1	1.5	V
<b>Dynamic characteristics</b>						
$dV_D/dt$	rate of rise of off-state voltage	$V_{DM} = 536\text{ V}$ ; $T_j = 150\text{ }^{\circ}\text{C}$ ; ( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform; gate open circuit	80	-	-	V/ $\mu\text{s}$

## ●Limiting values

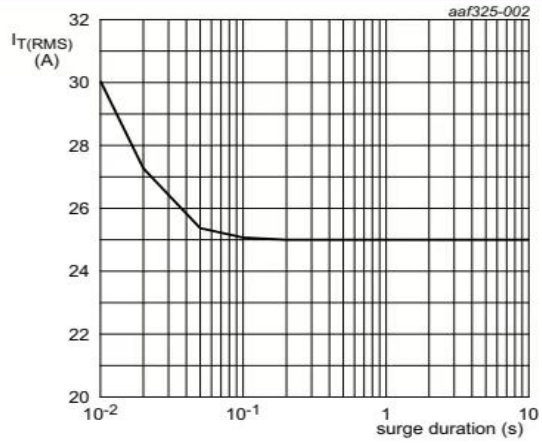
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DRM}$	repetitive peak off-state voltage		-	800	V
$V_{RRM}$	repetitive peak reverse voltage		-	800	V
$I_{T(AV)}$	average on-state current	half sine wave; $T_{mb} \leq 128\text{ }^{\circ}\text{C}$ ;	-	16	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_{mb} \leq 128\text{ }^{\circ}\text{C}$ ; Fig. 1; Fig. 2; Fig. 3	-	25	A

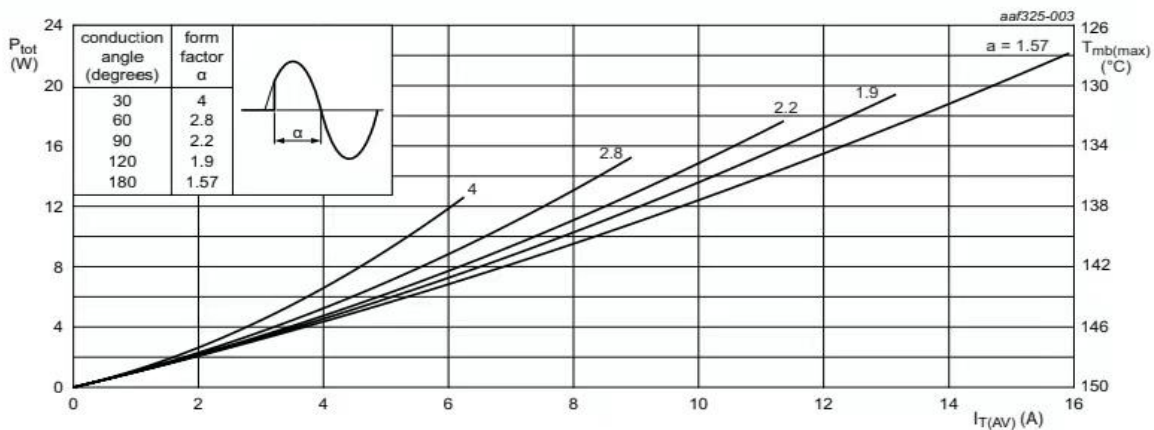
$I_{TSM}$	non-repetitive peak on-state current	half sine wave; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$ ; $t_p = 10\text{ ms}$ ; Fig. 4; Fig. 5	-	300	A
		half sine wave; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$ ; $t_p = 8.3\text{ ms}$	-	330	A
$\int t$	$\int t$ for fusing	$t_p = 10\text{ ms}$ ; SIN	-	450	$\text{A}^2\text{s}$
$di_T/dt$	rate of rise of on-state current	$I_G = 20\text{ mA}$	-	200	$\text{A}/\mu\text{s}$
$I_{GM}$	peak gate current		-	5	A
$V_{RGM}$	peak reverse gate voltage		-	5	V
$P_{GM}$	peak gate power		-	20	W
$P_{G(AV)}$	average gate power	over any 20 ms period	-	0.5	W
$T_{stg}$	storage temperature		-40	150	$^{\circ}\text{C}$
$T_j$	junction temperature		-	150	$^{\circ}\text{C}$



**Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values**

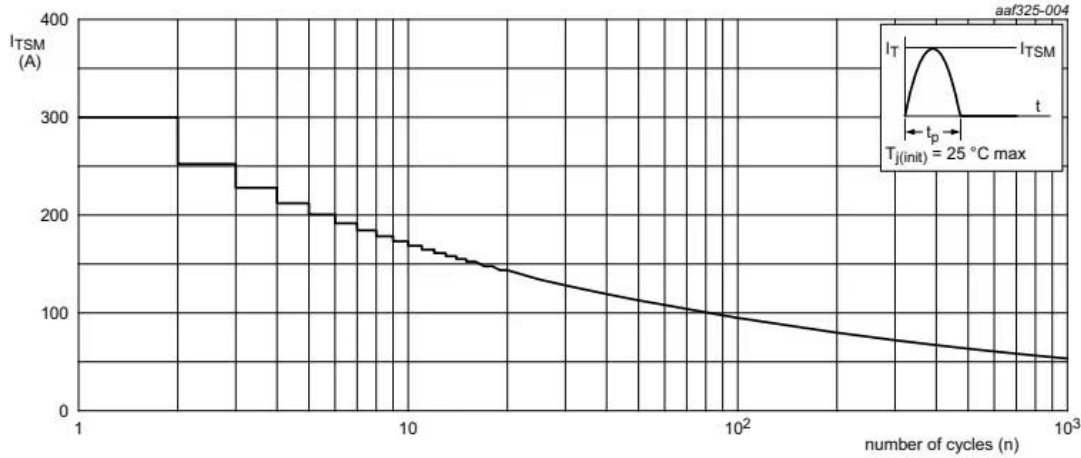


**Fig. 2. RMS on-state current as a function of surge duration; maximum values**  
 $f = 50\text{ Hz}$ ;  $T_{mb} = 128\text{ }^{\circ}\text{C}$



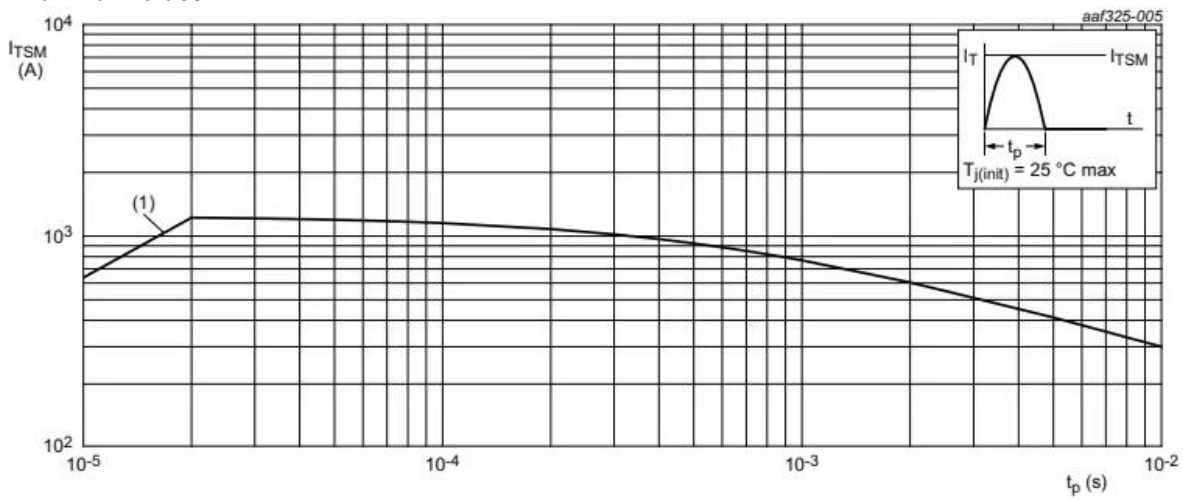
$\alpha = \text{conduction angle}$   
 $a = \text{form factor} = I_{T(RMS)} / I_{T(AV)}$

**Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values**



f = 50 Hz

Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



$t_p \leq 20 \text{ ms}$  ;  
(1)  $di_T/dt$  limit

Fig. 5. Non-repetitive peak on-state current as a function of pulse duration; maximum values

### •Thermal Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 6	-	-	1	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	60	-	K/W

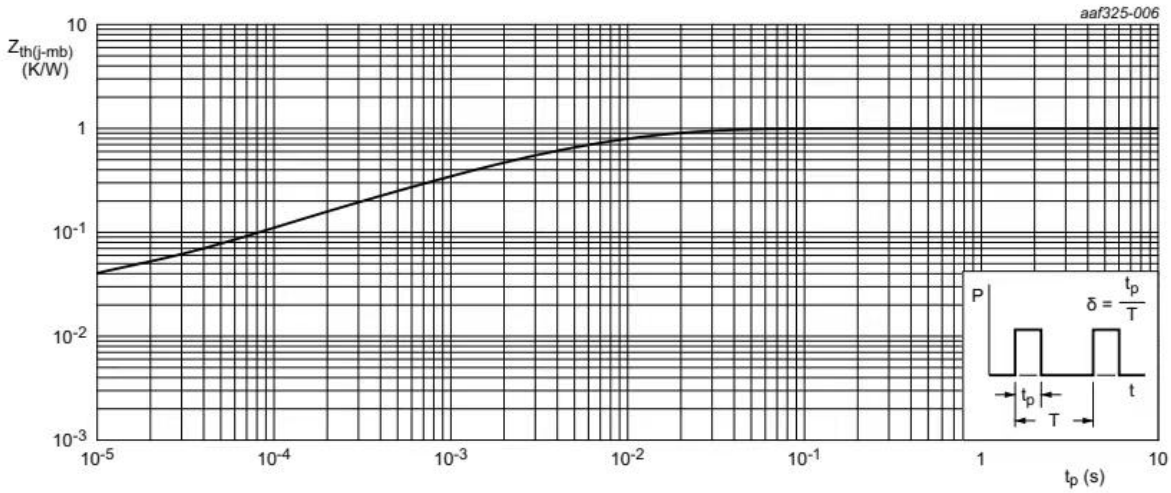
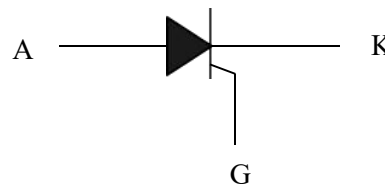
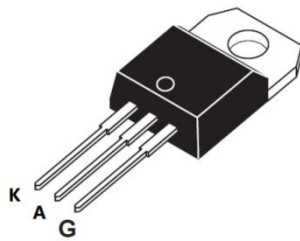
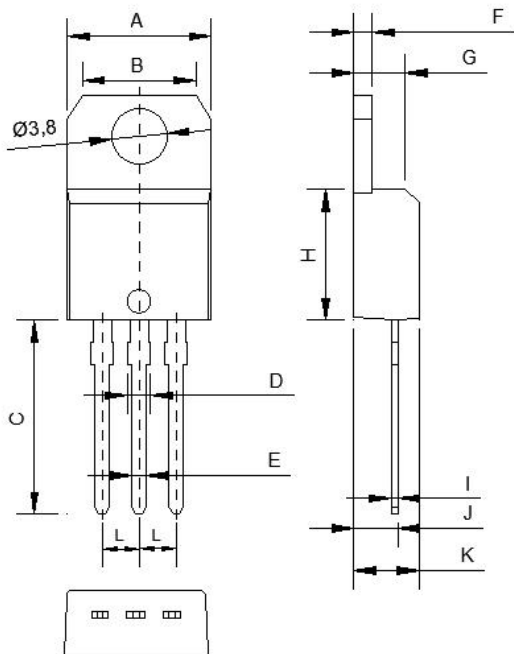


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse duration

●Symbol



●PACKAGE MECHANICAL DATA



Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	9.85	9.95	0.388	0.392
B	7.75	7.85	0.305	0.309
C	13.20	13.40	0.520	0.528
D	1.56	1.60	0.061	0.063
E	0.96	1.00	0.038	0.039
F	1.23	1.27	0.048	0.050
G	3.45	3.55	0.136	0.140
H	8.95	9.05	0.352	0.356
I	0.44	0.46	0.017	0.018
J	2.98	3.02	0.117	0.119
K	4.40	4.50	0.173	0.177
L	2.53	2.55	0.100	0.100